

LOCTITE**BERGQUIST**NEXT GEN
GAP FILLERS

BERGQUIST® GAP FILLER TGF 2900 LVO

2.9 W/m-K, 2-component, silicone-based and low volatile liquid thermal interface material

1 CUSTOMER NEEDS

- Improved thermal performance with **low thermal resistivity**
- Easy **processability**
- Flexibility to deploy in different applications **reducing supply chain complexity**
- **Low outgassing** material

2 HENKEL SOLUTIONS & SUSTAINABILITY

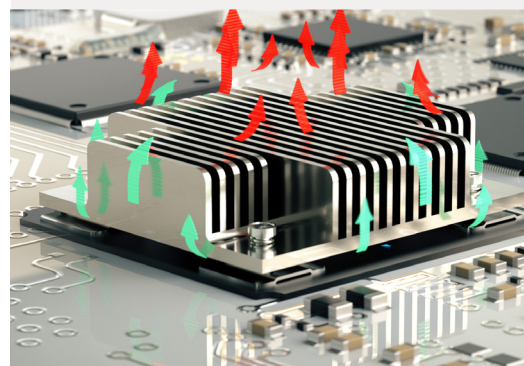
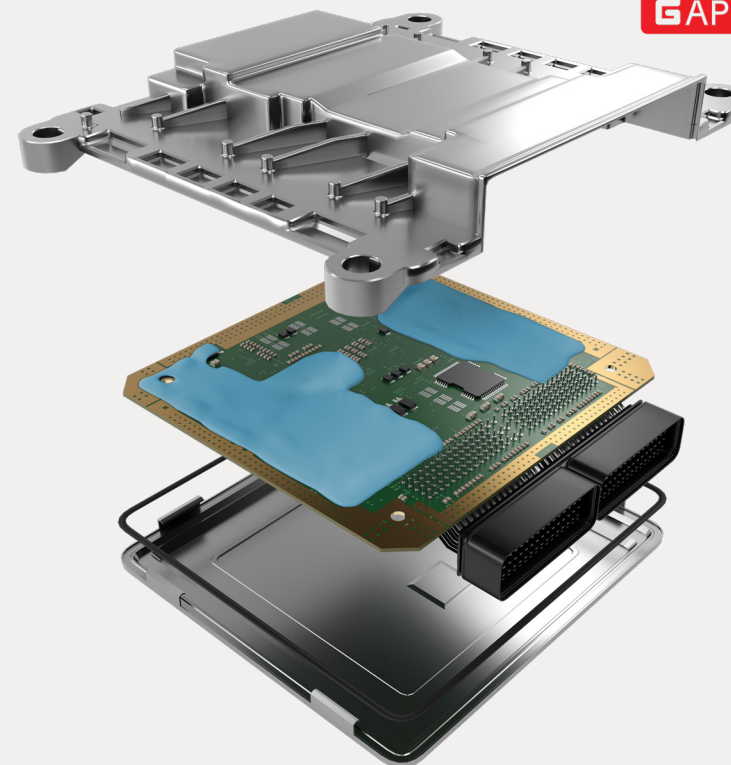
- Possibility to go to **ultra-thin bondline** thickness of < 50 µm
- Easy and robust to dispense with **longer working time** reducing scrap
- **Go-to product** at medium thermal conductivity
- **Low volatile** silicone-based thermal interface material

[CONTACT US TO LEARN MORE](#)

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